

### Description

The NTTFS015N04C-HXY uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

### **General Features**

 $V_{DS} = 40V I_D = 50A$  $R_{DS(ON)} < 14m\Omega V_{GS} = 10V$ 

#### Application

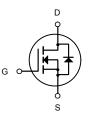
Battery protection

Load switch

Uninterruptible power supply

#### SSSG DD DD DD DD DD DD DD DD DD DD





N-Channel MOSFET

#### Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
NTTFS015N04C-HXY	DFN5X6-8L	50N04 XXX YYYY	5000

#### Absolute Maximum Ratings (Tc=25 °C unless otherwise noted)

Symbol	Parameter	Rating	Units
Vds	Drain-Source Voltage	40	V
Vgs	Gate-Source Voltage	±20	V
l₀@Tc=25°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	50	А
I <sub>D</sub> @Tc=100°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	38	А
Ідм	Pulsed Drain Current <sup>2</sup>	160	A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	50	mJ
Тѕтс	Storage Temperature Range	-55 to 175	°C
TJ	Operating Junction Temperature Range	-55 to 175	°C



N-Channel Enhancement Mode MOSFET

### **Thermal Characteristic**

Thermal Resistance, Junction-to-Case <sup>(Note 2)</sup>	R <sub>θJC</sub>	1.76	°C/W
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## Electrical Characteristics (T<sub>c</sub>=25<sup>°</sup>C unless otherwise noted)

Parameter	Parameter Symbol Condition		Min	Тур	Max	Unit
Off Characteristics	I					I
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V I <sub>D</sub> =250µA	40	40 -		V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =40V,V <sub>GS</sub> =0V -		-	1	μA
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V,V <sub>DS</sub> =0V	-	-	±100	nA
On Characteristics (Note 3)	I					1
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> ,I <sub>D</sub> =250µA	1	1.6	2.5	V
Drain-Source On-State Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =30A	-	11	14	mΩ
Forward Transconductance	<b>G</b> FS	V <sub>DS</sub> =5V,I <sub>D</sub> =20A	30	-	-	S
Dynamic Characteristics (Note4)						
Input Capacitance	Clss		-	1540	-	PF
Output Capacitance	C <sub>oss</sub>	$V_{DS}=25V, V_{GS}=0V,$	-	171	-	PF
Reverse Transfer Capacitance	C <sub>rss</sub>	F=1.0MHz	-	115	-	PF
Switching Characteristics (Note 4)	I					1
Turn-on Delay Time	t <sub>d(on)</sub>		-	5.0	-	nS
Turn-on Rise Time	tr	V <sub>DD</sub> =20V,I <sub>D</sub> =20A,R=1Ω	-	24	-	nS
Turn-Off Delay Time	t <sub>d(off)</sub>	$V_{GS}$ =10V, $R_{GEN}$ =3 $\Omega$	-	38	-	nS
Turn-Off Fall Time	t <sub>f</sub>		-	12	-	nS
Total Gate Charge	Qg	N/ 00X/1 00A	-	24	-	nC
Gate-Source Charge	Q <sub>gs</sub>	$V_{DS}=30V,I_{D}=30A,$	-	5.9	-	nC
Gate-Drain Charge	Q <sub>gd</sub>	V <sub>GS</sub> =10V	-	3.6	-	nC
Drain-Source Diode Characteristics		1				
Diode Forward Voltage (Note 3)	V <sub>SD</sub>	V <sub>GS</sub> =0V,I <sub>S</sub> =30A	-	-	1.2	V
Diode Forward Current (Note 2)	Is		-	-	48	A
Reverse Recovery Time	t <sub>rr</sub>	TJ = 25°C, IF =30A	-	9		nS
Reverse Recovery Charge	Qrr	di/dt = 100A/µs <sup>(Note3)</sup>	-	15		nC
Forward Turn-On Time	t <sub>on</sub>	Intrinsic turn-on time is negligible (turn-on is dominated by LS+LI				

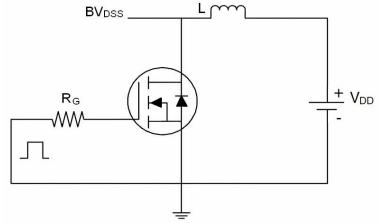
#### Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- **2.** Surface Mounted on FR4 Board,  $t \le 10$  sec.
- 3. Pulse Test: Pulse Width  $\leq$  300µs, Duty Cycle  $\leq$  2%.
- 4. Guaranteed by design, not subject to production
- 5.  $E_{AS}$  condition: Tj=25  $^\circ\!\mathrm{C}$  ,V\_{DD}=30V,V\_G=10V,L=0.5mH,Rg=25\Omega

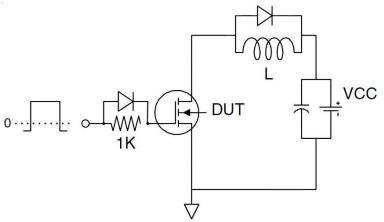


# Test circuit

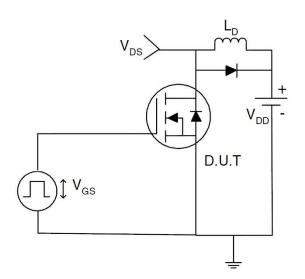
1) E<sub>AS</sub> test Circuits



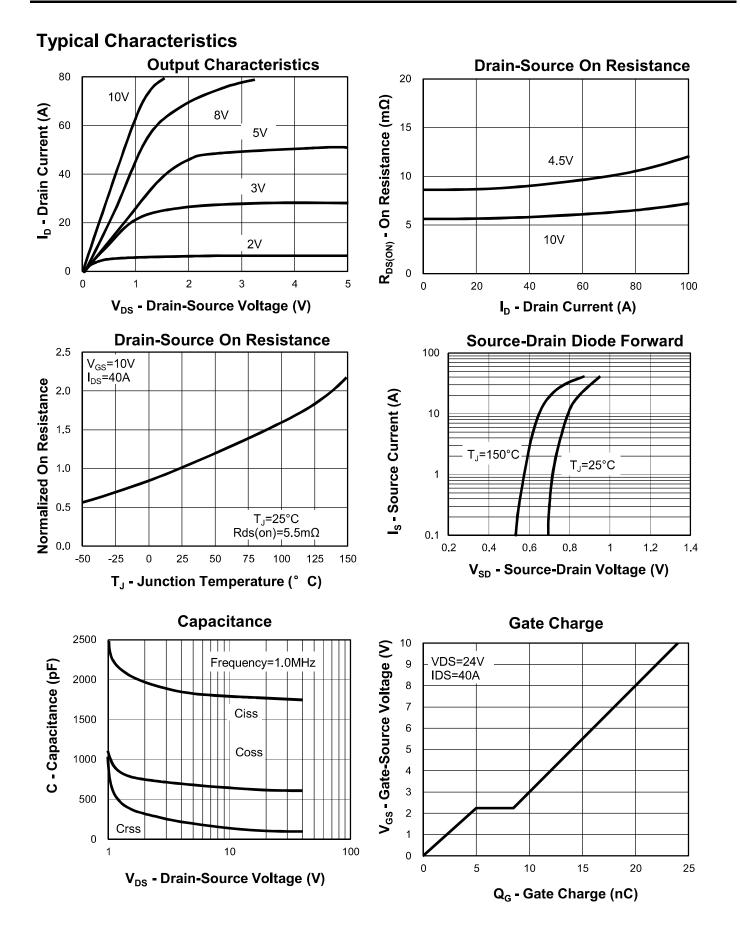
# 2) Gate charge test Circuit



3) Switch Time Test Circuit



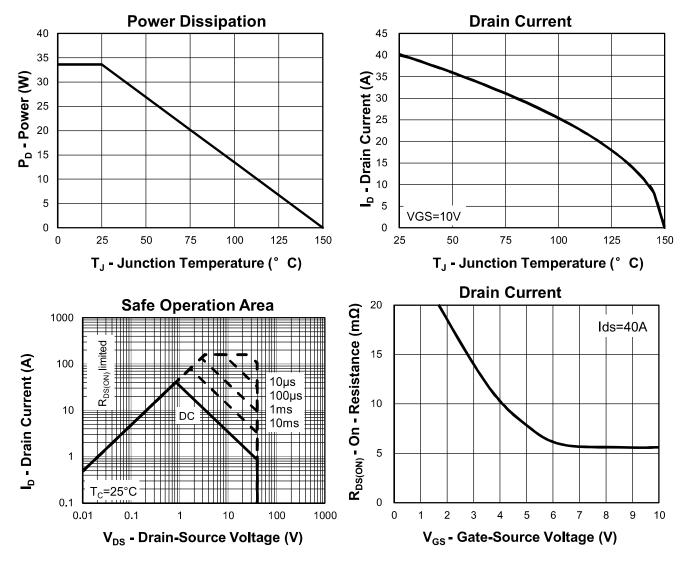




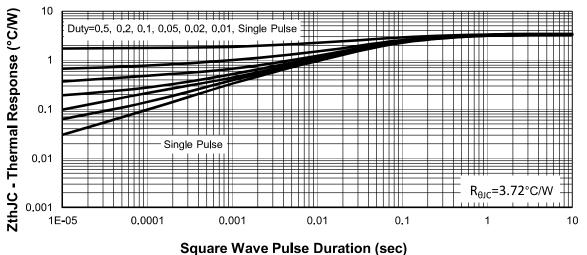


# NTTFS015N04C-HXY N-Channel Enhancement Mode MOSFET

# **Typical Characteristics**

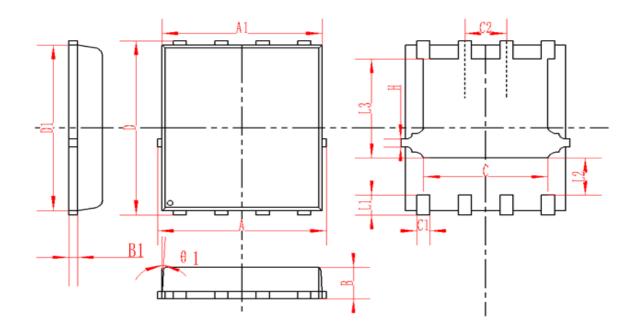








# DFN5X6-8L Package Information



SYMBOL		MM			INCH	
STIVIDOL	MIN	NOM	MAX	MIN	NOM	MAX
А	4.95	5	5.05	0.195	0.197	0.199
A1	4.82	4.9	4.98	0.190	0.193	0.196
D	5.98	6	6.02	0.235	0.236	0.237
D1	5.67	5.75	5.83	0.223	0.226	0.230
В	0.9	0.95	1	0.035	0.037	0.039
B1	0.254REF		0.010REF			
С	3.95	4	4.05	0.156	0.157	0.159
C1	0.35	0.4	0.45	0.014	0.016	0.018
C2	1.27TYP		0.5TYP			
θ1	8°	10°	12°	8°	10°	12°
L1	0.63	0.64	0.65	0.025	0.025	0.026
L2	1.2	1.3	1.4	0.047	0.051	0.055
L3	3.415	3.42	3.425	0.134	0.135	0.135
Н	0.24	0.25	0.26	0.009	0.010	0.010



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